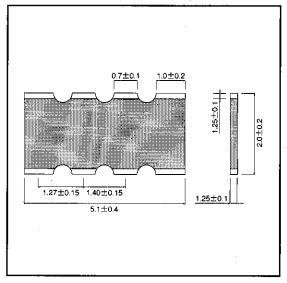
# Multi-layer ceramic chip capacitors MNA24 (2012×4 size chip network capacitor)

#### Features

- 1)Area ratio is approximately 43% smaller than that of chip MCH21, enabling high-density mounting.
- 2) Mounting costs are reduced.
- 3)Use of convex electrodes prevents solder bridging during mounting, and makes it easy to perform a visual inspection of the mounted component. Also facilitates automatic inspection.
- 4)Solder-plated terminals offer superior wetting properties and resistance to soldering heat.
- 5) Each element is independent to ensure a wide range of circuit applications.
- 6)Can be packed on taping.

#### External dimensions (Units: mm)



#### Structure

# External electrode III (solder-plated layer) External electrode II (barrier layer) External electrode I (thick membrane layer)

#### Equivalent circuits

(Floating capacitance between the terminals) is with 0.5% of nominal capacitance value

#### Makeup of the part number

When ordering, please specify the part number.
 Please check to be sure of what combination of

features you wish to order.

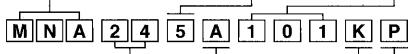
Fill in the blanks from left to right.

Series name

Symbol Voltage 5 50V Rated voltage Three-digif number indicates the number of picotarads. The first two digits are the significant digits; the last digit gives the number of zeros.

Examples: 101 = 100 pF, 221 = 220 pF, 471 = 470 pF

Nominal capacitance



Shape Dimensions		Capacitance-temperature characteristics			
Symbol	Nominal dimensions (mm)	Symbol	EIA code	Operating temp. range (°C)	Temp. coefficient
24	5.1×2.0	Α	COG	-55~ <del>+</del> 125	0±30ppm / °C

Capacitance tolerance				
	Symbol	Tolerance		
	K	±10%		

Packa	ing specifications			
Symbol	Packaging style	Basic ordering unit(pcs		
Р	Plastic taping (≠180mm)	3000pcs		

#### Capacitance range

(Units:pF)

		I	
Dom No	Thickness (mm)	A (COG) characteristics	
Part No.		50V	
MNA24 1.25±0.1		100, 220, 470	
Tolerance (%)		K (±10).	

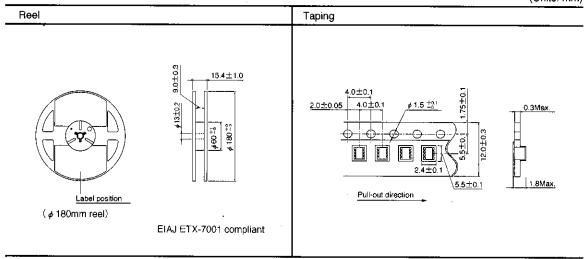
#### ● Characteristics (for temperature compensated)

Temperature characteristics		A (COG)	Test methods/conditions (based on JIS C 5102)	
Operating temperature range		−55°C ~+125°C	·	
Nominal capacitance (C)		Must be within the specified tolerance range.	Measured at room temperature and standard humidity	
Dissipation factor (Ian δ )		100/(400+20C)% or less : Less than 30 pF 0.1% or less ; 30 pF or larger	Based on paragraph 7.8 and paragraph 9.  1000pF or lessMeasurement frequency: 1±0.1MHz  Measurement voltage: 1±0.1Vrms.  Over 1000pF Measurement frequency: 1±0.1kHz  Measurement voltage: 1±0.1Vrms.	
Insulation resistance (IR)		10,000 M $\Omega$ or larger, or 500 $\Omega$ F or larger, whichever is smaller	Measurement is made after rated voltage Based on paragraph 7.6 is applied for 60±5s.	
Withstanding voltage		The insulation must not be damaged.	Apply 300% of the rated voltage Based on paragraph 7.1 for 1 to 5s then measure.	
Temperature characteristics		Within 0±30ppm / 'C	The temperature coefficients in table 12, paragraph 7.12 are calculated at 20°C and high temperature.	
Terminal adherence		No detachment or signs of detachment.	Based on JIS C 6429, Appendix 1.  Apply 5N (0.51 kgf) for 10 ±1s in the direction Indicated by the arrow.	
	Appearance	There must be no mechanical damage.	Chip is mounted to a board in the manner shown on the right, subjected to vibration (type A in paragraph 8.2),	
Resistance to vibration	Rate of capacitance change	Must be within initial tolerance.		
	Dissipation factor	Must satisfy initial specified value.	and measured 24±2 hrs later. Board	
Solderability		At least 3/4 of the surface of the two terminals must be covered with new solder.	Soldering temperature Based on paragraph 9.13: 235±5°C Soldering time: 2±0.5s	
	Appearance	There must be no mechanical damage.	Based on JIS C 6429, Appendix 3, Soldering temperature: 260±5℃ Soldering time: 5±0.5s Preheating: 150±10℃ for 1 to 2 min.	
	Rate of capacitance change	±2.5% or less, or ±0.25 pF or less, whichever is larger		
Resistance	Dissipation factor	Must satisfy initial specified value.		
to solder heat	Insulation resistance	10,000 M $\Omega$ or larger, or 500 $\Omega$ F or larger, whichever is smaller		
	Withstanding voltage	The insulation must not be damaged.	1	
	Appearance	There must be no mechanical damage.	Based on paragraph 9.3.	
Temperature	Rate of capacitance change	±2.5% or less, or ±0.25 pF or less, whichever is larger.		
cycling	Dissipation factor	Must satisfy initial specified value.	Number of cycles: 10 Capacitance measured after 24±2 hrs.	
	Insulation resistance	10,000 MΩ or larger, or 500 ΩF or larger, whichever is smaller	,	
Humidity load test	Appearance	There must be no mechanical damage.	Based on paragraph 9.9, Test temperature : 40±2°C Relative humidity: 90% - 95% Applied voltage: rated voltage Test time: 500 to 524 hrs.	
	Rate of capacitance change	$\pm$ 7.5% or less, or $\pm$ 0.75 pF or less, whichever is larger.		
	Dissipation factor	0.5% or less		
	Insulation resistance	500 M $\Omega$ or larger, or 25 $\Omega$ F or larger, whichever is smaller	Capacitance measured after 24±2 hrs.	
High- temperature load test	Appearance	There must be no mechanical damage.	Based on paragraph 9.10, Test temperature	
	Rate of capacitance change	±3.0% or less, or ±0.3 pF or less, whichever is larger.	: Max. operating temp.  Applied vottage: rated voltage x 200%	
	Dissipation factor	0.3% or less	Test time: 1,000 to 1,048 hrs.	
	Insulation resistance	10,000 M $\Omega$ or larger, or 50 $\Omega$ F or larger, whichever is smaller	Capacitance measured after 24±2 hrs.	

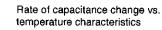


#### Packaging

(Units: mm)



#### Electrical characteristics



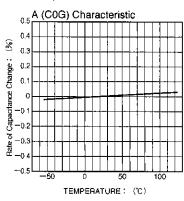


Fig.1

## Pate of capacitance change vs. DC voltage characteristics

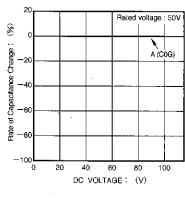


Fig.2

## Impedance vs. frequency characteristics

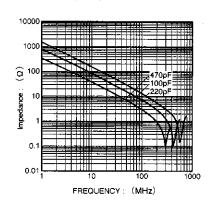
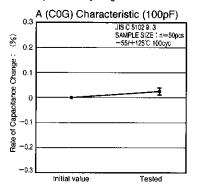


Fig.3

Ceramic Capacitors

# Electrical characteristics Temperature cycling test



0.6

JIS C 5102 9.3
SAMPLE SIZE : n=50pcs
-55/+125°C 100cyc

0.4

0.4

0.5

0.5

0.7

0.7

Initial value

Tested

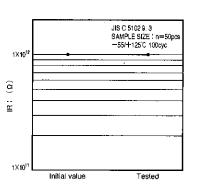
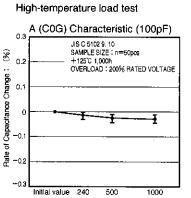
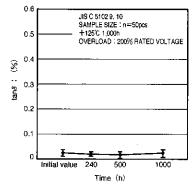


Fig.4 Rate of capacitance change

Fig.5 Dissipation factor

Fig.6 Insulation resistance





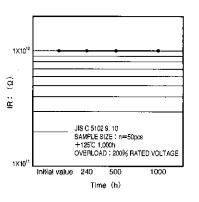
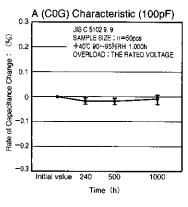
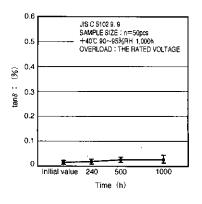


Fig.7 Rate of capacitance change Humidity load test

Fig.8 Dissipation factor

Fig.9 Insulation resistance





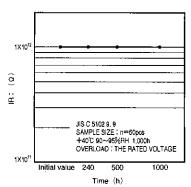


Fig.10 Rate of capacitance change

Fig.11 Dissipation factor

Fig.12 Insulation resistance

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